

Procedure for CMP on chips

The CMP tool is mostly dedicated to 4", 6" and 8" wafers.

There are 2 options for processing chips or wafers with different dimensions: either using a dedicated 15 mm x 15 mm holder, or sticking the chip on a dummy wafer with a special film adhesive.

Wafergrip film adhesive



Wafergrip adhesives (https://www.dynatex.com/wafergrip-adhesives_8_113_26194.html) are available at the IPHYS cleanrooms (<https://www.epfl.ch/schools/sb/research/iphys/fr/nos-services/salles-blanches/>). They are used to temporarily bond substrates to carrier wafers.

The process involves heating the assembly to 110°C while applying pressure on the stack.

The equipment used to perform this step is the "Mini Reflow Solder System UniTemp RSS-450-110" (<https://www.epfl.ch/schools/sb/research/iphys/fr/nos-services/salles-blanches/iii-v-lab/unitemp-rss/>).

Please contact the IPHYS staff in order to get trained on the equipment.